

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISO1H801G	**Issued**	3. July 2019
MA#	MA003420052		
Package	PG-DSO-36-21	**Weight***	2105.01 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	16.733	0.79	0.79	7949	7949
chip_2	inorganic material	silicon	7440-21-3	1.123	0.05	0.05	533	533
chip_3	inorganic material	silicon	7440-21-3	1.164	0.06	0.06	553	553
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		738	
	non noble metal	iron	7439-89-6	31.066	1.48		14758	
	non noble metal	copper	7440-50-8	1261.410	59.93	61.50	599242	614922
wire	noble metal	gold	7440-57-5	4.222	0.20	0.20	2006	2006
encapsulation	organic material	carbon black	1333-86-4	1.523	0.07		723	
	plastics	epoxy resin	-	70.040	3.33		33273	
	inorganic material	silicondioxide	60676-86-0	689.739	32.77	36.17	327665	361661
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7147	7147
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	306	306
solder	non noble metal	tin	7440-31-5	0.101	0.00		48	
	noble metal	silver	7440-22-4	0.151	0.01		72	
	non noble metal	lead	7439-92-1	9.819	0.47	0.48	4665	4785
glue	plastics	Polyimide	26023-21-2	0.290	0.01	0.01	138	138
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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